TG-NSP25
Preliminary Data Sheet

Description

TG-NSP25 is an ultra conformable silicone-free putty type gap filler. It is designed for when heat transfer is needed between delicate components where the pressure must be minimised and silicone contamination cannot be tolerated. TG-NSP25 is designed to fill gaps from 0.25 – 8mm with little or no stress generated. The non-silicone formulation will adhere to all surfaces, such as metal housings, ceramic and plastic IC packages and FR4 boards to give a low thermal resistance path for heat transfer.

TG-NSP25 is available in 30cc syringes, 6 and 12oz cartridges and 5 gallon pails.

Property	TG_NSP25	Test Method
Colour	White	-
Description	One part silicone free putty	-
Viscosity /mPas	5,000,000	-
Density / gcm^3	2.5	ASTM D792
Thermal Conductivity / W/mk	2.5	ASTM D5470
D4-10 /ppm	0	GC / MS
TML / %	0.2%	ASTM E595
CVCM / %	0.1	ASTM E595
Volume Resistivity / Ohm cm^1	10^{14}	
Working Temperature / °C	-50 to 150°	

Tel: +44 20 8133 2062 Email: sales@tglobaltechnology.com Web: www.tglobaltechnology.com Skype: tglobal.technology